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(54) Title: REDUCTION OF SURFACE OXIDATION DURING ELECTROPLATING

(57) Abstract: Methods of providing improved metal coatings or metal deposits on a substrate, improvements in plating solutions that are used to provide such metal deposits and articles of the metal-coated substrates. The solderability of the metal coating is enhanced by incorporating trace amounts of phosphorus in the metal coating to reduce surface oxide formation during subsequent heating and thus enhance long term solderability of the metal coating. The phosphorus is advantageously provided in the metal coating by incorporating a source of phosphorus in a solution that is used to provide the metal coating on the substrate, and the metal coating is then provided on the substrate from the solution.

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